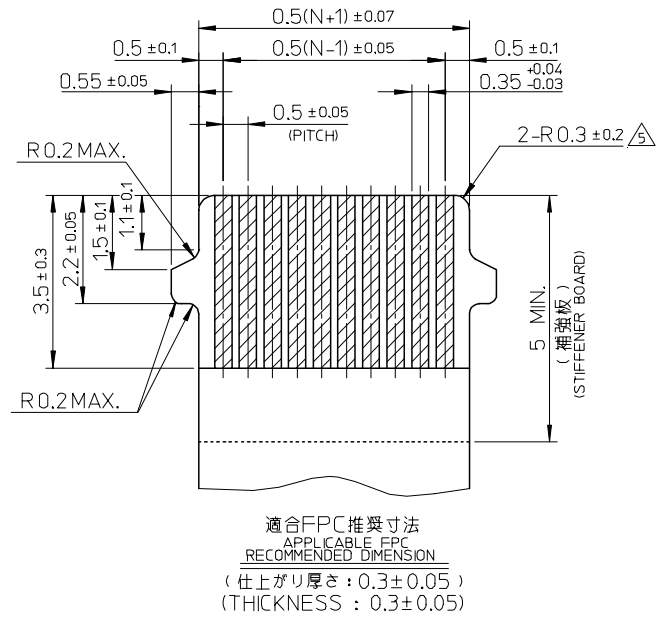
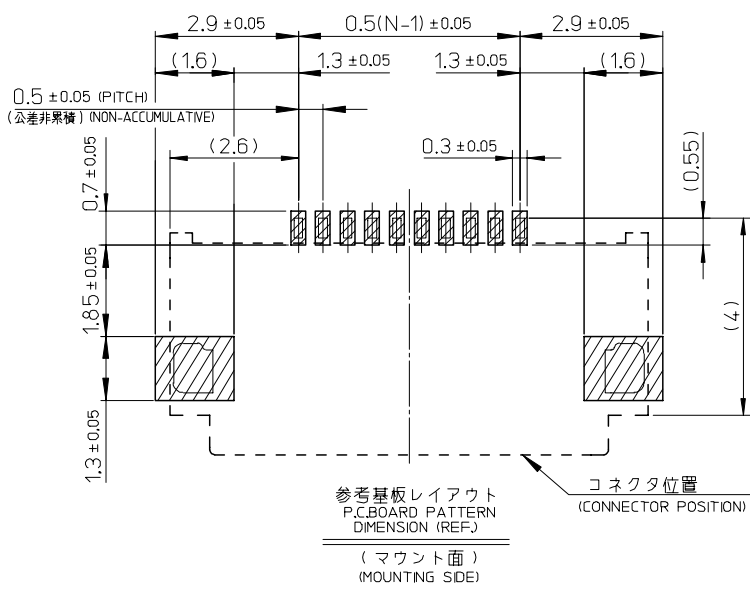


アクチュエータを開口した状態  
(WHEN ACTUATOR IS OPENED)

40.1	36.5	41.7	502500-7411	74
38.1	34.5	39.7	502500-7011	70
C	B	A	MATERIAL NO.	CIRCUIT

REVISED EC NO: J2007-3430 DRWN: AOYAGI CHKD: YMAEDA APPR: NUKITA	DESCRIPTION 2007/06/15 2007/06/18 2007/06/18	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY YTAKAYASU	DATE 2007/03/01	TITLE 0.5 FPC CONN. ZIF E/O HSG ASS'Y (H=2.5)				
		10 OVER 30 UNDER	± ---	CHECKED BY HIRATA	DATE 2007/03/01	MOLEX INCORPORATED				
		30 OVER	± ---	APPROVED BY MSASAO	DATE 2007/03/01	DOCUMENT NO. SD-502500-001				
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2				
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



**注記 NOTES**

1. 使用材料 MATERIAL  
ハウジング : 液晶ポリマー ガラス充填, UL94-V0(ベージュ)  
HOUSING LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0(BEIGE)  
アクチュエータ : PPS ガラス充填, UL94-V0(茶)  
ACTUATOR PPS GLASS FILLED, UL94V-0(BROWN)  
ターミナル : リン青銅(t=0.18)  
TERMINAL PHOSPHOR BRONZE  
金具 : リン青銅(t=0.15)  
FITTING NAIL PHOSPHOR BRONZE
2. めっき仕様 PLATING  
ターミナル TERMINAL  
ニッケル下地金めっき  
GOLD(Au) OVER NICKEL(Ni) PLATING.  
  
金具 FITTING NAIL  
ニッケル下地銅めっき  
TIN(Sn) OVER NICKEL(Ni) PLATING.
3. エンボスタープ梱包時は、アクチュエータが閉じた状態とする。  
IN THE PACKAGE, ACTUATOR OF PART 502500-\*\*\*11 SHOULD BE CLOSED.

- △ R0.3は、FPC 導体部にかからないこと。  
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
6. N: 極数 N: CIRCUIT.
  7. ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT

FPC について:  
打ち抜き方向は導体側から補強板側を推奨します。  
導体部については軟銅箔35µmまたは50µmを推奨します。  
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25µmを推奨します。  
接着剤は熱硬化接着剤を推奨します。  
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。

ABOUT FPC  
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
RECOMMENDED CONDUCTOR SPEC :  
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.  
RECOMMENDED MATERIAL/THICKNESS.  
STIFFENER FILM : POLYIMIDE  
BASE FILM THICKNESS : 25µm  
BONDING AGENT : THERMOSETTING BONDING AGENT  
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

△ パターン剥離止め用金具  
FITTING NAIL FOR PREVENTION OF  
PEELING OF P.C.B. PATTERN.

REVISED EC NO: J2007-3430 DRWN: AOYAGI CHKD: MAEDA APPR: NUKITA	DESCRIPTION 2007/06/15 2007/06/18 2007/06/18	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	---	METRIC		
		10 UNDER	± ---	DRAWN BY	DATE	TITLE		
		10 OVER 30 UNDER	± ---	Y TAKAYASU	2007/03/01	0.5 FPC CONN. ZIF E/0 HSG ASS'Y (H=2.5)		
		30 OVER	± ---	CHECKED BY	DATE			
				H HIRATA	2007/03/01			
				APPROVED BY	DATE			
				M SASAO	2007/03/01	MOLEX INCORPORATED		
		ANGULAR	± --- °	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1	SD-502500-001	2 OF 2		
A	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						